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Front Matter: Volume 10085

, "Front Matter: Volume 10085," Proc. SPIE 10085, Components and Packaging for Laser Systems III, 1008501 (20 March 2017); doi: 10.1117/12.2276037

SPIE.

Event: SPIE LASE, 2017, San Francisco, California, United States

PROCEEDINGS OF SPIE

Components and Packaging for Laser Systems III

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Paul O. Leisher
Editors

31 January–2 February 2017
San Francisco, California, United States

Sponsored and Published by
SPIE

Volume 10085

Proceedings of SPIE 0277-786X, V. 10085

SPIE is an international society advancing an interdisciplinary approach to the science and application of light.

Components and Packaging for Laser Systems III, edited by Alexei L. Glebov, Paul O. Leisher, Proc. of SPIE
Vol. 10085, 1008501 · © 2017 SPIE · CCC code: 0277-786X/17/\$18 · doi: 10.1117/12.2276037

Proc. of SPIE Vol. 10085 1008501-1

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Author(s), "Title of Paper," in *Components and Packaging for Laser Systems III*, edited by Alexei L. Glebov, Paul O. Leisher, Proceedings of SPIE Vol. 10085 (SPIE, Bellingham, WA, 2017) Seven-digit Article CID Number.

ISSN: 0277-786X
ISSN: 1996-756X (electronic)

ISBN: 9781510606111
ISBN: 9781510606128 (electronic)

Published by

SPIE

P.O. Box 10, Bellingham, Washington 98227-0010 USA
Telephone +1 360 676 3290 (Pacific Time) · Fax +1 360 647 1445
SPIE.org

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Contents

vii *Authors*
ix *Conference Committee*

SESSION 1	LASER DIODE PACKAGING I: JOINT SESSION WITH CONFERENCES 10085 AND 10086
------------------	--

10085 02	Assessment of factors regulating the thermal lens profile and lateral brightness in high power diode lasers (Invited Paper) [10085-1]
10085 04	Complete indium-free CW 200W passively cooled high power diode laser array using double-side cooling technology [10085-3]

SESSION 2	LASER DIODE PACKAGING II
------------------	---------------------------------

10085 05	Narrow-line diode laser packaging and integration in the NIR and MIR spectral range (Invited Paper) [10085-4]
10085 06	Compact diode laser module at 1116 nm with an integrated optical isolation and a PM-SMF output [10085-5]
10085 08	Artificial neural network assisted laser chip collimator assembly and impact on multi-emitter module beam parameter product [10085-7]

SESSION 3	LASER DIODE PACKAGING III
------------------	----------------------------------

10085 09	Reliable QCW diode laser arrays for operation with high duty cycles [10085-8]
10085 0A	Thermal characteristics of compact conduction-cooled high power diode laser array packages [10085-9]
10085 0B	Collimation optics for high power blue laser diodes [10085-10]
10085 0C	Optoelectronic packaging of single photon avalanche diodes [10085-2]
10085 0D	The smile effect reduction of diode laser bar by bare bar curve control [10085-12]

SESSION 4	LASER DIODE PACKAGING IV
------------------	---------------------------------

10085 0F	Narrow linewidth diode laser modules for quantum optical sensor applications in the field and in space (Invited Paper) [10085-14]
10085 0G	Optical components for tailoring beam properties of multi-kW diode lasers [10085-15]
10085 0I	Optimization of microchannel cooler of high power diode laser array package [10085-17]

SESSION 5 COMPONENTS AND PACKAGING FOR HIGH POWER/ENERGY LASERS I

- 10085 OJ **Application specific beam profiles: new surface and thin-film refinement processes using beam shaping technologies (Invited Paper)** [10085-18]
- 10085 OK **Optics for multimode lasers with elongated depth of field** [10085-19]

SESSION 6 COMPONENTS AND PACKAGING FOR HIGH POWER/ENERGY LASERS II

- 10085 OM **1.5kW linear polarized on PM fiber and 2kW on non-PM fiber narrow linewidth CW diffraction-limited fiber amplifier** [10085-40]
- 10085 ON **SRS modeling in high power CW fiber lasers for component optimization** [10085-22]
- 10085 OP **Complex holographic elements in photo-thermo-refractive glass for the visible spectral region** [10085-24]
- 10085 OQ **High power laser source for atom cooling based on reliable telecoms technology with all fibre frequency stabilisation** [10085-25]
- 10085 OR **The SMAT fiber laser for industrial applications** [10085-26]

SESSION 7 COMPONENTS AND PACKAGING FOR PULSED HIGH POWER/ENERGY LASERS

- 10085 OS **Environmentally stable seed source for high power ultrafast laser (Invited Paper)** [10085-27]

SESSION 8 COMPONENTS AND PACKAGING FOR LASER BEAM ENGINEERING

- 10085 OW **Design and evaluation of a diffractive beam splitter for dual-wavelength laser processing** [10085-31]
- 10085 OY **Active alignment of DOE based structured light application in consumer electronics** [10085-33]
- 10085 OZ **Simultaneous position and angle control for outgoing laser beam design using two galvanometer mirrors** [10085-34]
- 10085 10 **Beam shaping with numerically optimized photonic crystals** [10085-35]

POSTER SESSION

- 10085 12 **The implementation of the combined high-speed laser scanning for SRS-lidar** [10085-37]
- 10085 13 **Simple, compact, and low cost CO₂ laser driven by fast high voltage solid state switch for industrial application** [10085-38]
- 10085 14 **Cladding pump light stripper study for high power fiber laser applications** [10085-39]

Authors

Numbers in the index correspond to the last two digits of the seven-digit citation identifier (CID) article numbering system used in Proceedings of SPIE. The first five digits reflect the volume number. Base 36 numbering is employed for the last two digits and indicates the order of articles within the volume. Numbers start with 00, 01, 02, 03, 04, 05, 06, 07, 08, 09, 0A, 0B...0Z, followed by 10-1Z, 20-2Z, etc.

Amako, J., 0W
Ashok, Nandam, 14
Assmann, Christian, 05
Bawamia, A., 0F
Bayer, Andreas, 0G
Biesenbach, Jens, 09, 0G
Bodem, Christian, 0G
Bordenyuk, Andrey, 0S
Braglia, Andrea, 08
Brecher, C., 0Y
Brochu, G., 0N
Cheng, Jian, 0D
Crump, P., 02
De La Cruz, Joel, 0M
Demmer, D., 0C
Ding, Jianwu, 0R
Dionne, R., 0N
Divliansky, Ivan, 0P
Dürsch, Sascha, 0G
Elizarov, Valentin, 12
Farries, Mark, 0Q
Faßbender, Wilhelm, 09, 0G
Faucher, M., 0N
Forrer, H., 0B
Forrer, M., 0B
Gadonas, Roaldas, 10
Gailevičius, Darius, 10
Gapontsev, Valentin, 0M, 0S
Giudice, A., 0C
Glebov, Leonid B., 0P
Grishkanich, Aleksandr, 12
Han, Seungryong, 14
Haslett, T., 0C
Hauschild, Dirk, 0J
Hayakawa, Tomohiko, 0Z
Hettler, N., 0Y
Hofmann, Julian, 06
Huber, M., 0B
Hubrich, Ralf, 0G
Iakovlev, Alexey, 12
Ishikawa, Masatoshi, 0Z
Jedzejczyk, Daniel, 06
Jia, Guannan, 0D
Jimenez, Alvaro, 05
Kascheev, Sergey V., 12
Kemke, R., 02
Kindervater, Tobias, 0G
Kissel, Heiko, 09
Könning, Tobias, 09, 0G
Köhler, Bernd, 0G
Kompan, Fedor, 0P
Krüger, M., 0F
Kürbis, Ch., 0F
Küster, Matthias, 0G
Laskin, Alexander, 0K
Laskin, Vadim, 0K
Lee, Yeung Lak, 14
Legg, Thomas, 0Q
Liang, Xuejie, 04, 0I
Liu, Hui, 04
Liu, Jinghui, 0R
Liu, Xingsheng, 04, 0A, 0I
Liu, Yalong, 04
Lotz, Jens, 09
Luo, Xiaoying, 0D
Mahnkopf, S., 0C
Mak, Andrey, 12
Milde, Tobias, 05
Morin, M., 0N
Moser, H., 0B
Müller, T., 0Y
Nakano, Hitoshi, 13
Nie, Zhiqiang, 0I
O'Gorman, James, 05
Ostrun, Aleksei, 0K
Paschke, Katrin, 06
Patterson, Steve, 09
Peckus, Martynas, 10
Perrone, Guido, 08
Peters, A., 0F
Plappert, Nora, 0G
Platonov, Nikolai, 0M
Purlys, Vytautas, 10
Rieprich, J., 02
Rossi, Giammarco, 08
Sacher, Joachim R., 05
Sahm, Alexander, 06
Samartsev, Igor, 0S
Sauer, S., 0Y
Schiemangk, M., 0F
Shin, WooJin, 14
Simmerle, G., 0C
Smirnov, Leonid, 12
Smirnov, Vadim, 0P
Smol, R., 0F
Stacke, Niklas, 05
Staliunas, Kestutis, 10
Tanaka, Miyu, 13

Tei, Masaya, 13
Tomm, J., 02
Tränkle, G., 0F
Trépanier, F., 0N
Uno, Kazuyuki, 13
Villeneuve, A., 0N
Wang, Jingwei, 04, 0A, 0I
Wang, Zhiyong, 0D
Wei, Xi, 0R
Werner, Nils, 06
Wicht, A., 0F
Winterfeldt, M., 02
Wolf, Paul, 0G
Wu, Dihai, 04, 0I
Wuest, P., 0B
Xu, Jun, 0R
Yagodkin, Roman, 0M
Yao, Shun, 0D
Yu, Dongshan, 04
Yu, Hao, 08
Yusim, Alexander, 0M
Zah, Chung-en, 04
Zhang, Pu, 0A, 0I
Zhevlakov, Aleksandr, 12
Zhu, Pengfei, 04
Zhu, Qiwen, 0A
Zontar, D., 0Y

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- 1 Laser Diode Packaging I: Joint Session with Conferences 10085 and 10086
Paul O. Leisher, Rose-Hulman Institute of Technology (United States)
Robert Martinsen, nLIGHT Corporation (United States)
- 2 Laser Diode Packaging II
Martin Forrer, FISBA AG (Switzerland)
- 3 Laser Diode Packaging III
Chungen Zah, Focuslight Technologies, Inc. (China)
- 4 Laser Diode Packaging IV
Joseph L. Dallas, Avo Photonics, Inc. (United States)
- 5 Components and Packaging for High Power/Energy Lasers I
Christian V. Poulsen, NKT Photonics Inc. (United States)
- 6 Components and Packaging for High Power/Energy Lasers II
Alexander V. Laskin, AdlOptica Optical Systems GmbH (Germany)
- 7 Components and Packaging for Pulsed High Power/Energy Lasers
Alexander Yusim, IPG Photonics Corporation (United States)
- 8 Components and Packaging for Laser Beam Engineering
Evan Robert Hale, CREOL, University of Central Florida (United States)